SN74ALVC00-Q1 QUADRUPLE 2-INPUT POSITIVE-NAND GATE

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Qualified for Automotive Applications

- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17

DOR PW PACKAGE (TOP VIEW) 14 🛛 V_{CC} 1A [1B **[**]2 13**∏** 4B 1Y **∏**3 12**∏** 4A 11 1 4Y 2A 10**∏** 3B 2B 9 🛮 3A 2Y **[**]6 8 T 3Y **GND**

description/ordering informatiom

The SN74ALVC00 quadruple 2-input positive-NAND gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The device performs the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION[†]

T _A	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
4000 +- 0500	SOIC - D	Tape and reel	SN74ALVC00IDRQ1	ALVC00I
-40°C to 85°C	TSSOP - PW	Tape and reel	SN74ALVC00IPWRQ1	VA00I

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

FUNCTION TABLE (each gate)

INP	JTS	OUTPUT
Α	В	Υ
Н	Н	L
L	X	Н
Х	L	Н

logic diagram, each gate (positive logic)





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[‡] Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Notes 1 and 2)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, $I_{ K }(V_1 < 0)$	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V_{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$			
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
V_{I}	Input voltage	•	0	3.6	V	
Vo	Output voltage		0	V_{CC}	V	
		V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-12		
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		12		
l _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA	
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate	·		5	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	v _{cc}	MIN	TYP [†]	MAX	UNIT			
	I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.2						
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.2						
V _{OH}	I _{OH} = -6 mA		2.3 V	2						
V _{OH}			2.3 V	1.7			V			
	I _{OH} = −12 mA		2.7 V	2.2						
			3 V	2.4						
	I _{OH} = -24 mA		3 V	2						
.,	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2				
	I _{OL} = 4 mA		1.65 V			0.45	;			
	I _{OL} = 6 mA		2.3 V			0.4	0.4 V			
V _{OL}	1 40 ··· A		2.3 V			0.7	V			
	I _{OL} = 12 mA		2.7 V							
	I _{OL} = 24 mA		3 V			0.55				
I _I	V _I = V _{CC} or GND		3.6 V			±5	μΑ			
Icc	$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			10	μΑ			
ΔI_{CC}	One input at V _{CC} – 0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μΑ			
C _i	V _I = V _{CC} or GND		3.3 V		4.5		pF			

 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

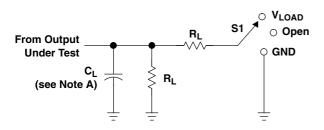
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.2		V _{CC} =	2.7 V	V _{CC} = ± 0.3		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{pd}	A or B	Y	1	4.4	1	2.8		3.2	0.5	3	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST	ONDITIONS	V _{CC} = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$	LINIT	
	PARAMETER		CNDITIONS	TYP TYP TYP			UNIT	
C _{pd}	Power dissipation capacitance per gate	$C_L = 0$,	f = 10 MHz	20	21	23	pF	

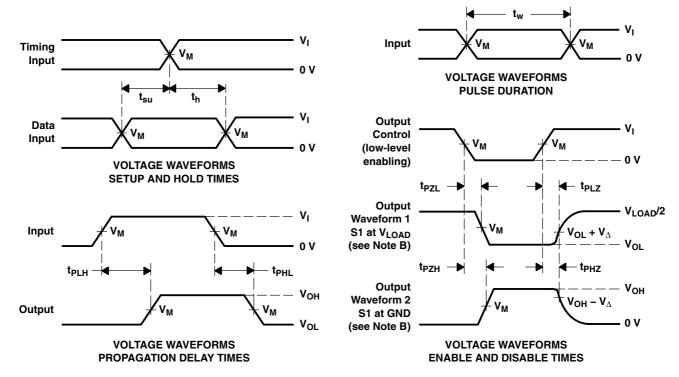
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	IN	PUT	V	V	•		V
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	RL	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	V _{CC}	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
$2.5\pm0.2~V$	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ALVC00IPWRG4Q1	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC00I
SN74ALVC00IPWRG4Q1.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC00I

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN74ALVC00-Q1:

Catalog: SN74ALVC00

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

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● Enhanced Product : SN74ALVC00-EP

NOTE: Qualified Version Definitions:

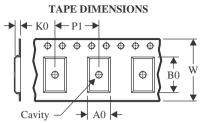
- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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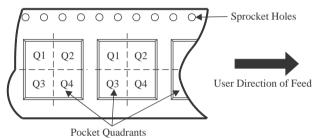
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

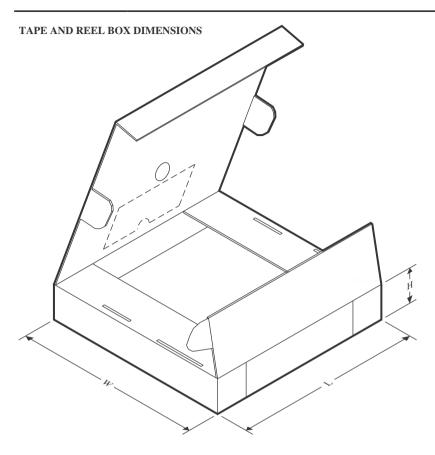


*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVC00IPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

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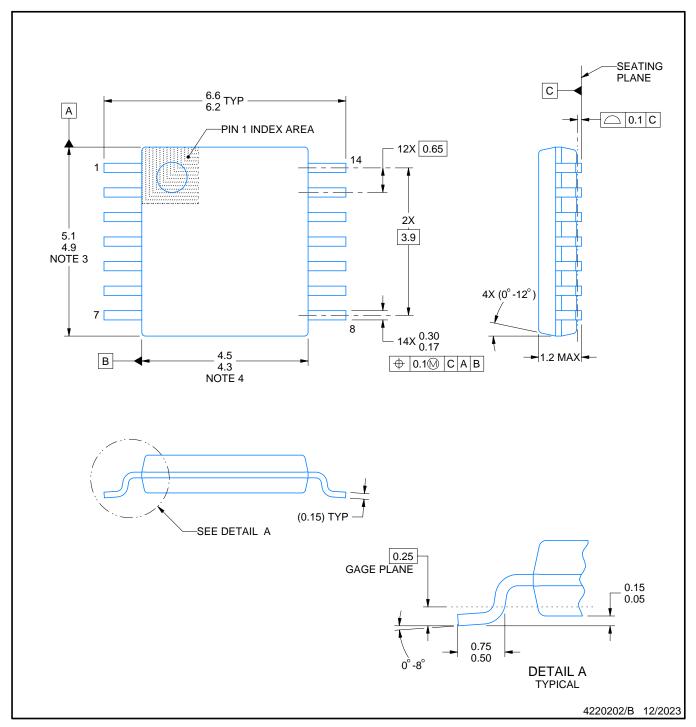


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVC00IPWRG4Q1	TSSOP	PW	14	2000	353.0	353.0	32.0



SMALL OUTLINE PACKAGE



NOTES:

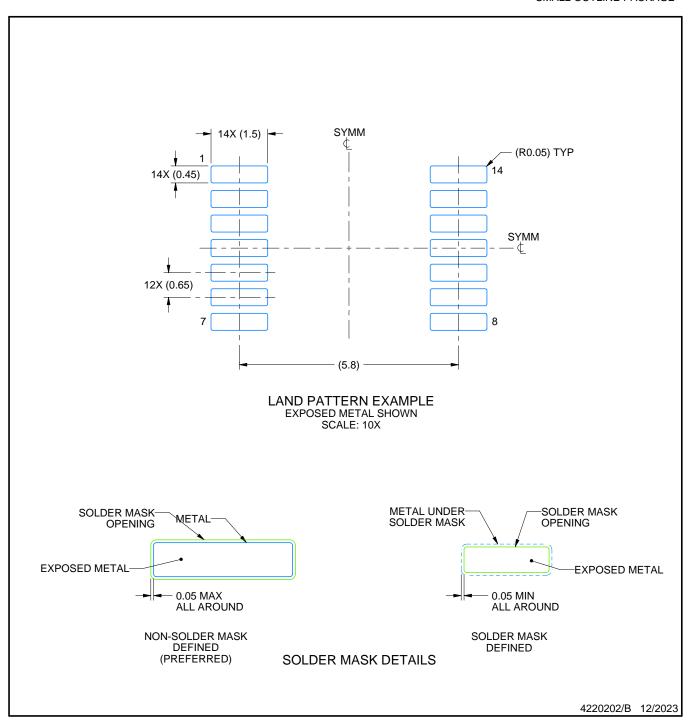
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



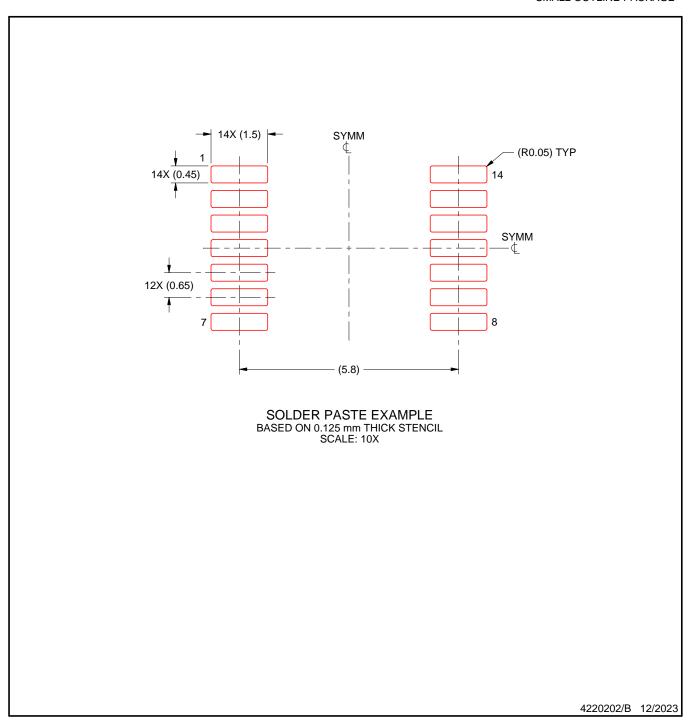
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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